NCE N-Channel Enhancement Mode Power MOSFET

GENERAL FEATURES

• $V_{DS} = 60V, I_D = 0.3A$

 $R_{DS(ON)} < 3\Omega @ V_{GS} = 4.5V$

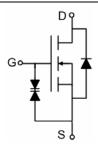
 $R_{DS(ON)}$ < 2 Ω @ V_{GS} =10V

ESD Rating: HBM 2500V

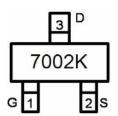
- High Power and current handing capability
- Lead free product is acquired
- Surface Mount Package

Application

- Direct Logic-Level Interface: TTL/CMOS
- Drivers: Relays, Solenoids, Lamps, Hammers, Display, Memories, Transistors, etc.
- Battery Operated Systems
- Solid-State Relays



Schematic diagram



Marking and pin Assignment



SOT-23 top view

Package Marking And Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
7002K	2N7002K	SOT-23	Ø180mm	8 mm	3000 units

Absolute Maximum Ratings (TA=25℃unless otherwise noted)

5 \	,			
Parameter	Symbol	Limit	Unit	
Drain-Source Voltage	V _{DS}	60	V	
Gate-Source Voltage	V _G s	±20	V	
Prain Current Continuous® Current Bulged (Note 1)	I _D	0.3	Α	
Drain Current-Continuous@ Current-Pulsed (Note 1)	I _{DM}	0.8	Α	
Maximum Power Dissipation	P _D	0.35	W	
Operating Junction and Storage Temperature Range	T_{J}, T_{STG}	-55 To 150	$^{\circ}\!\mathbb{C}$	

Thermal Characteristic

Thermal Resistance, Junction-to-Ambient (Note 2)	R _{θJA}	350	°C/W
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Electrical Characteristics (TA=25°C unless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =250μA	60			V



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2N7002K

Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =60V,V _{GS} =0V			1	μA
Gate-Body Leakage Current	I _{GSS}	V _{GS} =±20V,V _{DS} =0V			±10	uA
On Characteristics (Note 3)						
Gate Threshold Voltage	$V_{GS(th)}$	V _{DS} =V _{GS} ,I _D =250µA	1	1.5	2.5	V
Drain-Source On-State Resistance	Ь	V _{GS} =4.5V, I _D =0.2A		1.2	3	Ω
	$R_{DS(ON)}$	V _{GS} =10V, I _D =0.5A		1.1	2	Ω
Forward Transconductance	g FS	V _{DS} =10V,I _D =0.2A	0.1			S
Dynamic Characteristics (Note4)	·					
Input Capacitance	C _{lss}	\/ =25\/\/ =0\/		21	50	PF
Output Capacitance	Coss	V _{DS} =25V,V _{GS} =0V, F=1.0MHz		11	25	PF
Reverse Transfer Capacitance	C _{rss}	F=1.0WHZ		4.2	5	PF
Switching Characteristics (Note 4)	·					
Turn-on Delay Time	t _{d(on)}			10		nS
Turn-on Rise Time	t _r	V_{DD} =30V, I_D =0.2A V_{GS} =10V, R_{GEN} =10 Ω		50		nS
Turn-Off Delay Time	$t_{\sf d(off)}$			17		nS
Turn-Off Fall Time	t _f			10		nS
Total Gate Charge	Q_g	V _{DS} =10V,I _D =0.3A, V _{GS} =4.5V		1.7	3	nC
Drain-Source Diode Characteristics	·		•	•	•	•
Diode Forward Voltage (Note 3)	V _{SD}	V _{GS} =0V,I _S =0.2A			1.3	V
Diode Forward Current (Note 2)	Is				0.2	Α

Notes:

- 1. Repetitive Rating: Pulse width limited by maximum junction temperature.
- 2. Surface Mounted on FR4 Board, t ≤ 10 sec.
- 3. Pulse Test: Pulse Width ≤ 300µs, Duty Cycle ≤ 2%.
- 4. Guaranteed by design, not subject to production

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

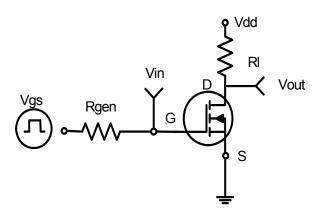


Figure 1:Switching Test Circuit

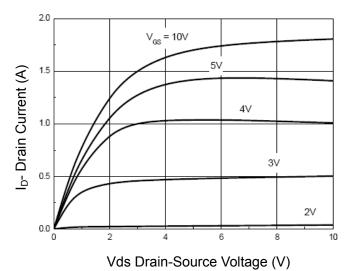


Figure 3 Output CHARACTERISTICS

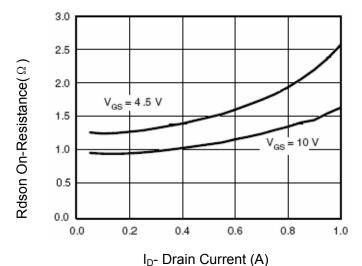


Figure 5 Drain-Source On-Resistance

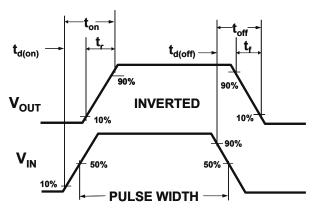


Figure 2:Switching Waveforms

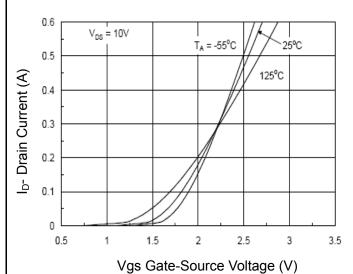
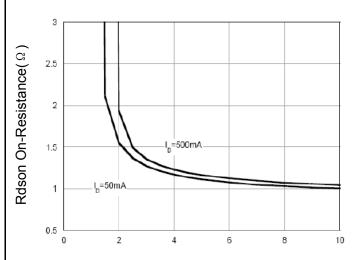
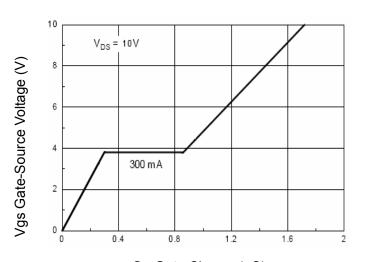


Figure 4 Transfer Characteristics



Vgs Gate-Source Voltage (V)
Figure 6 Rdson vs Vgs



Qg Gate Charge (nC) Figure 7 Gate Charge

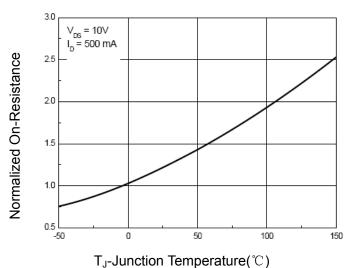


Figure 9 Drain-Source On-Resistance

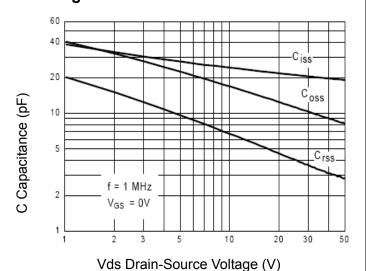
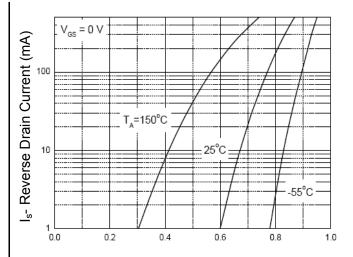
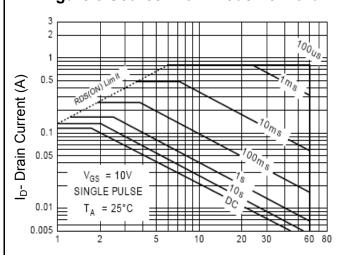


Figure 11 Capacitance vs Vds



Vsd Source-Drain Voltage (V)
Figure 8 Source-DrainDiode Forward



Vds Drain-Source Voltage (V)

Figure 10 Safe Operation Area

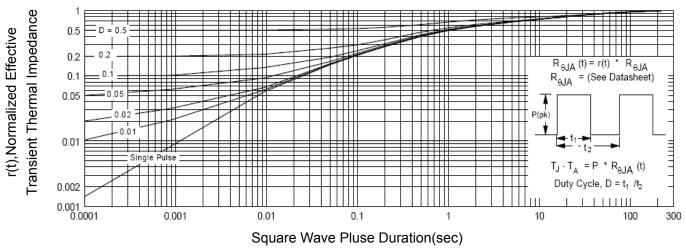
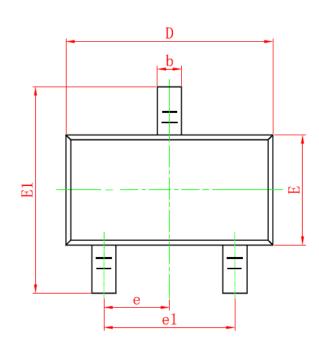
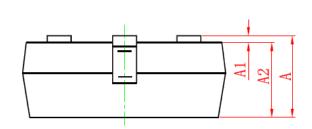


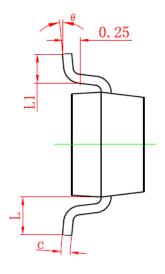
Figure 12 Normalized Maximum Transient Thermal Impedance

SOT-23 PACKAGE INFORMATION

Dimensions in Millimeters (UNIT:mm)







Symbol	Dimensions in Millimeters			
	MIN.	MAX.		
Α	0.900	1.150		
A 1	0.000	0.100		
A2	0.900	1.050		
b	0.300	0.500		
С	0.080	0.150		
D	2.800	3.000		
E	1.200	1.400		
E1	2.250	2.550		
е	0.950TYP			
e1	1.800	2.000		
L	0.550REF			
L1	0.300	0.500		
θ	0° 8°			

NOTES

- 1. All dimensions are in millimeters.
- 2. Tolerance ±0.10mm (4 mil) unless otherwise specified
- 3. Package body sizes exclude mold flash and gate burrs. Mold flash at the non-lead sides should be less than 5 mils.
- 4. Dimension L is measured in gauge plane.
- $5. \ Controlling \ dimension \ is \ millimeter, \ converted \ inch \ dimensions \ are \ not \ necessarily \ exact.$

Pb Free Product

2N7002K

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